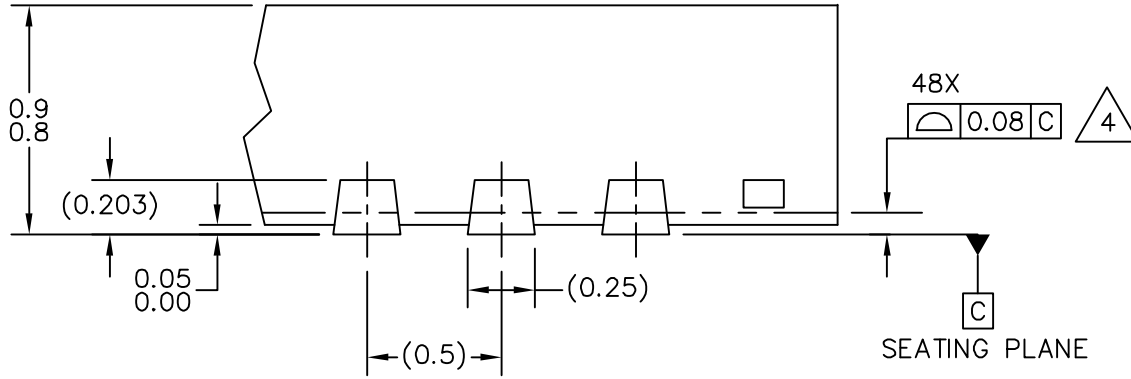


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ASA00757D	REV: A
	STANDARD: NON-JEDEC	
	SOT619-19	12 JAN 2016




DETAIL G
VIEW ROTATED 90°CW

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ASA00757D	REV: A
	STANDARD: NON-JEDEC	
	SOT619-19	12 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH FLAG.
5. MIN METAL GAP SHOULD BE 0.2 MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.5 PITCH, 48 TERMINAL		DOCUMENT NO: 98ASA00757D	REV: A
		STANDARD: NON-JEDEC	
		SOT619-19	12 JAN 2016